Samtec Releases New Interconnect Solutions Catalog

Samtec, Inc., a worldwide leader in the manufacture of electronic interconnect solutions, is pleased to announce the release of its new 2012 Interconnect Solutions Catalog. This latest edition includes a number of new products, new high speed test data and updated specifications on existing products, as well as an overview of Samtec’s ever-expanding RF product line.

In addition to new products and test data, the 2012 Interconnect Solutions Catalog highlights expanded product features such as lower cost plating options, new Rugged screw down options for board-to-board and discrete wire systems, and latching options for ultrafine pitch connectors.

Samtec’s comprehensive line of interconnect solutions includes Signal Integrity, Micro, Rugged and Power solutions for Board-to-Board, Cable, and Panel & I/O applications. These solutions are supported with Samtec’s integrated global service, manufacturing and quality strategies, along with its renowned Sudden Service®, ensuring the highest quality products, service and information.

**Featured New Products, Samtec 2012 Interconnect Solutions Catalog**

**Signal Integrity**
- 0,80mm Press Fit Micro Edge Card Socket
- PCIe® Active Optical Cable Assembly
- 0,80mm Edge Rate™ Pass-through Card Socket
- 0,50mm Q Strip® High Speed Right Angle Header and Socket
- 1,27mm SEARAY™ Press Fit Open Pin Field Array

**Micro**
- 0,50mm Slim Body, Low Profile Header and Socket
- 0,50mm Basic Blade & Beam Right Angle Header and Socket
- 0,50mm Flat Flexible Cable (FFC) Socket

**Rugged**
- 5,50mm/2,54mm High Power/Signal Combo Terminal and Socket
- 2,54mm Universal Discrete Wire Cable, Single and Double Row
- 3,81mm PowerStrip™ Dual Blade 15 Amp Power Right Angle Header and Socket
- 2mm PowerStrip™ Mini Power Combo Cable Assembly

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